Filename: BOM-PMP9080 REVD(001).xls

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Assembly Bill of Materials PMP9080

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
!PCB	1		Printed Circuit Board		XX####	Any
C1, C2, C5,	6	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, C0G/NP0, 0402	0402	C1005X7R1H104K	TDK
C7, C13, C14						
C3	1	1000uF	CAP, AL, 1000uF, 35V, +/-20%, 0.054 ohm, SMD	LH0	EMVY350GTR102MLH0 S	Nippon Chemi-Con
C4, C8	2	2.2uF	CAP, CERM, 2.2uF, 25V, +/-10%, X7R, 1206	1206	GRM31MR71E225KA93	MuRata
C6	1	47uF	CAP, CERM, 47uF, 6.3V, +/-20%, X5R, 1210	1210	C3225X5R0J476M	TDK
C9, C11	2	4.7uF	CAP, CERM, 4.7uF, 50V, +/-10%, X5R, 1206	1206	GRM319R61H475KA12	MuRata
C10	1	100uF	CAP, TA, 100uF, 10V, +/-20%, 0.1 ohm, SMD	7343-31	TPSD107M010R0100	AVX
C12	1	12pF	CAP, CERM, 12pF, 25V, +/-5%, C0G/NP0, 0402	0402	GRM1555C1E120JA01D	MuRata
C15		0.033uF	CAP, CERM, 0.033uF, 10V, +/-10%, X5R, 0402	0402	D	MuRata
D2		24V	Diode, Zener, 24V, 225mW, SOT-23	SOT-23	BZX84C24LT1G	ON Semiconductor
J1	1	B3P-VH	Connector, Top 3-pin, 156 mil spacing,	0.465 X 0.335 inch	B3P-VH	JST
J2	1		Connector, Receptacle, USB TYPE A, 4POS SMD	USB TYPE A CONNECTOR RECEPTACLE 4POS SMD		Mill-Max
J3, J4	2		Header, 100mil, 2x1, Tin plated, TH	Header, 2 PIN, 100mil, Tin	PEC02SAAN	Sullins Connector Solutions
L1	1	6.5uH	Inductor, Shielded Drum Core, Superflux, 6.5uH, 6A, 0.0225 ohm, SMD	WE-HC3	744314650	Wurth Elektronik eiSos
L2	1	{Value}	Inductor, Coulpled	0.050 x 0.080 inch	0805USB-xxxMB	Coilcraft
R1	1	16.9k	RES, 16.9k ohm, 1%, 0.063W, 0402	0402	CRCW040216K9FKED	Vishay-Dale
R2	1	80.6k	RES, 80.6k ohm, 1%, 0.063W, 0402	0402	CRCW040280K6FKED	Vishay-Dale
R3	1	0.05	RES, 0.05 ohm, 1%, 0.5W, 1206	1206	CRM1206-FZ-R050ELF	Bourns
R4, R5, R11, R12	4	1.00Meg	RES, 1.00Meg ohm, 1%, 0.063W, 0402	0402	CRCW04021M00FKED	Vishay-Dale
Ř6	1	49.9	RES, 49.9 ohm, 1%, 0.063W, 0402	0402	CRCW040249R9FKED	Vishay-Dale
R7	1	499k	RES, 499k ohm, 1%, 0.063W, 0402	0402	CRCW0402499KFKED	Vishay-Dale
R8, R9	2	100k	RES, 100k ohm, 5%, 0.063W, 0402	0402	CRCW0402100KJNED	Vishay-Dale
R10	1	1.00k	RES, 1.00k ohm, 1%, 0.25W, 1206	1206	CRCW12061K00FKEA	Vishay-Dale
R13, R100	2	1.00k	RES, 1.00k ohm, 1%, 0.063W, 0402	0402	CRCW04021K00FKED	Vishay-Dale
R14	1	3.01k	RES, 3.01k ohm, 1%, 0.063W, 0402	0402	CRCW04023K01FKED	Vishay-Dale
R101, R102	2	1.50k	RES, 1.50k ohm, 1%, 0.063W, 0402	0402		Vishay-Dale

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Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
TP1, TP2,	8	Red	Test Point, Multipurpose, Red, TH	Red Multipurpose	5010	Keystone
TP3, TP4,				Testpoint		
TP5, TP7,						
TP9, TP10						
TP6, TP8	2	Black	Test Point, Multipurpose, Black, TH	Black Multipurpose	5011	Keystone
				Testpoint		
U1	1		3.5 - 36V 3A Step-Down Converters with Low Quiescent	PWP0016F	LM43603PWP	Texas Instruments
			Current, PWP0016F			
U2	1	TPS254xRTE	IC, USB Charging Port Power Switch & Controller with	QFN-16	TPS254xRTE	TI
			Load Detect Feature.			
U3	1	TPD2E001DZDR	IC, Low-Capacitacnce 2-Chan ±15-kV ESD-Protection	SOP	TPD2E001DZDR	TI
			Array			
U4	1	LM2904M	Low Power Dual Op Amp	M08A_L	LM2904M	National Semiconductor

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